



Final Product Change Notification

201908007F01

Issue Date: 06-Sep-2019
Effective Date: 04-Dec-2019

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online

This notice is NXP Company Proprietary.



QUALITY

Change Category

- | | | | | |
|--|--|--|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input checked="" type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input type="checkbox"/> Other | | | |

**NXP-ATKL TEPBGA 27*27
Package Substrate
Singulation Method Change
From Mechanical Punch To
Saw**

Description of Change

NXP Semiconductors announces the change of substrate singulation method from mechanical punch to saw for the TEPBGA 27*27 package assembled in NXP-ATKL, Kuala Lumpur, Malaysia assembly facility. For more information about the substrate singulation method change, please refer to the "Communication Package" file attached.

The above change coincides with DeQuMa ID: SEM-PA-14 and SEM-EQ-01.

Reason for Change

The substrate singulation method change is required for customer supply assurance.

Identification of Affected Products

Product part number and marking identification does not change.

A visual comparison between substrate singulation using mechanical punch and saw is provided in the "Communication Package" file attached.

Product Availability

Sample Information

Samples are available upon request

Sample part numbers information is available in the "Communication Package" file attached.

Production

Planned first shipment 20-Dec-2019

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 06-Oct-2019.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Nuha Mohd. Adzhar

Position Product Engineer

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

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NXP Semiconductors

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Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Outline	Package Name	Status	Product Line
SPC5674FF3MNV3R	935310677518	SPC5674FF3MNV3R	4Mb Flash, 256k RAM, z7	SOT1527-2	BGA516	RFS	Auto Micro Processors
SPC5566MZP132	935313983557	SPC5566MZP132	3M FLASH,32K CACHE,128K	SOT1705-1	BGA416	RFS	Auto Micro Processors
SPC5676RDK3MVU1R	935314707518	SPC5676RDK3MVU1R	32 BIT 6M FLASH Z7 DUAL	SOT1705-1	BGA416	RFS	Auto Micro Processors
SPC5674FAMVY3	935315728557	SPC5674FAMVY3	4MB, 516BGA PF, 264mhz	SOT1527-2	BGA516	RFS	Auto Micro Processors
SPC5674FF3MVR3	935324463557	SPC5674FF3MVR3	4Mb Flash, 256k RAM, z7	SOT1705-1	BGA416	RFS	Auto Micro Processors
SPC5777MK0MVU8	935320541557	SPC5777MK0MVU8	QUAD CORE 8M FLASH	SOT1705-1	BGA416	RFS	Auto Micro Processors
SPC5673FF3MNV2	935311206557	SPC5673FF3MNV2	3M FLASH, 192K RAM, z7	SOT1527-2	BGA516	RFS	Auto Micro Processors
SPC5674FF3MNV3	935314555557	SPC5674FF3MNV3	4MB, 516BGA PF, 264mhz	SOT1527-2	BGA516	RFS	Auto Micro Processors
SPC5674FF3MNV3	935310677557	SPC5674FF3MNV3	4Mb Flash, 256k RAM, z7	SOT1527-2	BGA516	RFS	Auto Micro Processors
SPC5566MZP144	935309958557	SPC5566MZP144	3M FLASH,32K CACHE,128K	SOT1705-1	BGA416	RFS	Auto Micro Processors
SPC5676RDK3MNV1	935317596557	SPC5676RDK3MNV1	32 BIT 6M FLASH Z7 DUAL	SOT1527-2	BGA516	RFS	Auto Micro Processors
MPC5566MVR132	935324223557	MPC5566MVR132	3M FLASH,32K CACHE,128K	SOT1705-1	BGA416	RFS	Auto Micro Processors